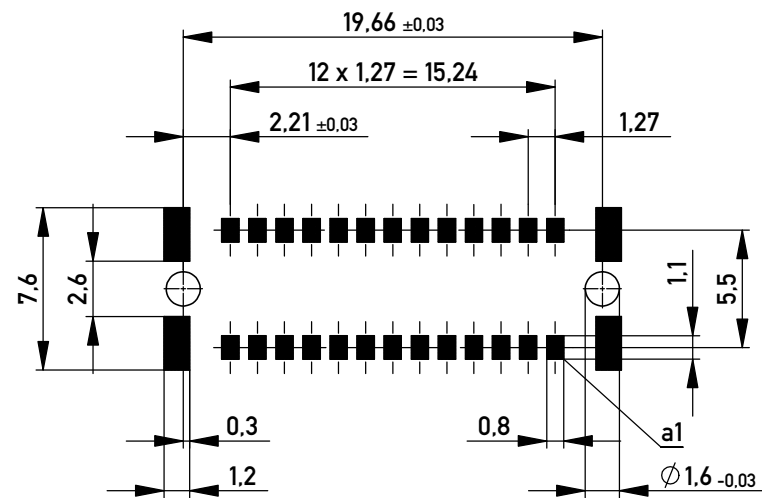


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



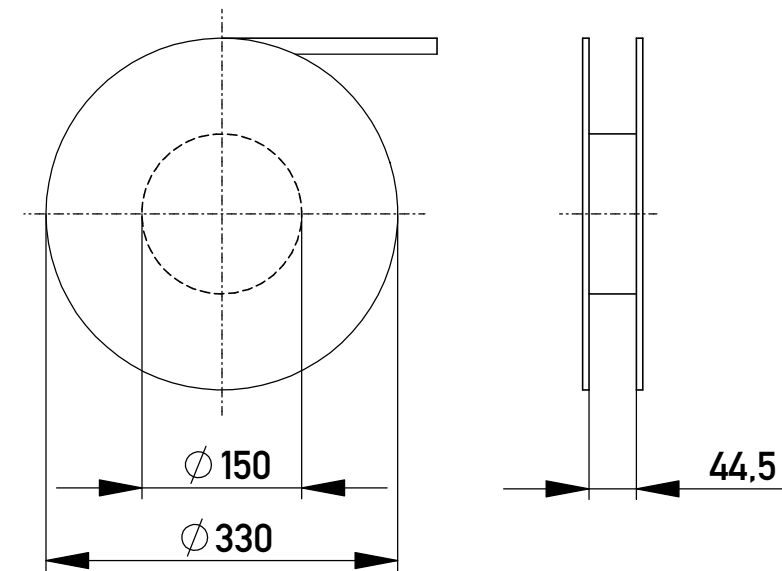
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

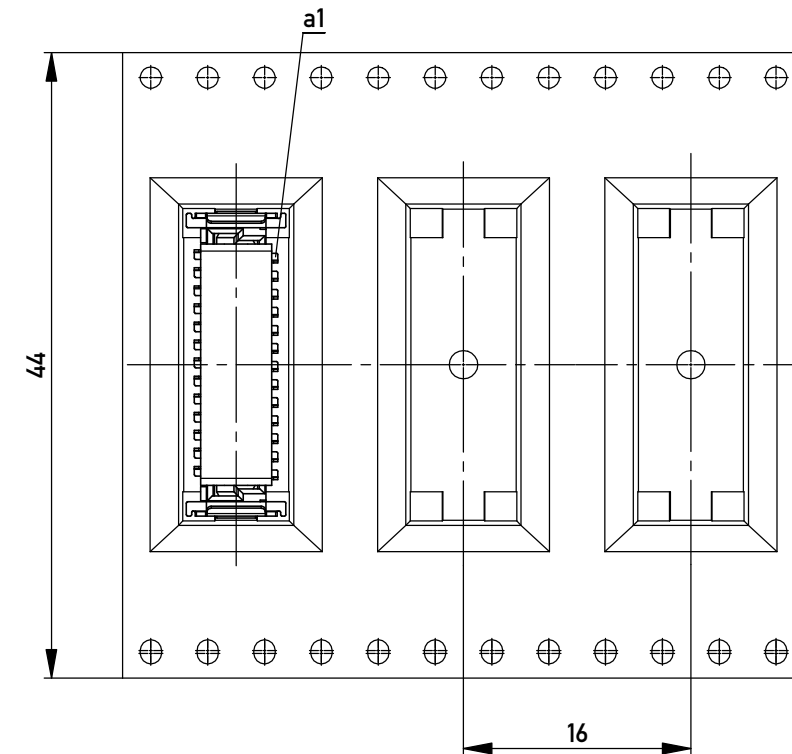
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

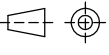

Verpackt in Gurtverpackung - *Tape on Reel Packaging*
Verpackungseinheit: 280 Stück - *Packaging unit: 280 pcs*



Abspulrichtung - *Reel off Direction*



BA 7-13 - 8mm Bauhöhe
type 7-13 - Low Profile

| | | | |
|--|---|---------------|---|
| Information: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using. | Tolerances  All Dimensions in mm | Scale 3:1 | Designation Messerl. SMC-Q 26-SMD-BA7-13 <i>Male SMC-Q 26-SMD-type7-13</i> |
| |  www.ERNI.com | | |
| c Index | 20.10.2011 Date | Class SMCQ | |

Copyright by ERNI GmbH
Proprietary notice pursuant to ISO 16016 to be observed.